


1 Substrate: 2.36mm  $\pm$ 0.178mm [0.093"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material.  
17 $\mu$ m [1/2 oz.] Cu clad. Au plating. RoHS.

2 Solder ball: Sn96.5Ag3.0Cu0.5



Description: Fine Pitch BGA Surface Mount Adaptor  
169 position 0.5mm pitch surface mount land pattern to solder balls.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>SF-BGA169H-B-05F Drawing</b>		Status: Released	Scale: 3:1	Rev: A
 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: S. Faiz		Date: 2/15/10	
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